



US00D703625S

(12) **United States Design Patent**  
**Lim et al.**

(10) **Patent No.:** **US D703,625 S**  
(45) **Date of Patent:** **\*\* Apr. 29, 2014**

- (54) **POWER SEMICONDUCTOR MODULE**
- (71) Applicant: **Samsung Electro-Mechanics Co., Ltd.**,  
Gyunggi-do (KR)
- (72) Inventors: **Jae Hyun Lim**, Gyunggi-do (KR);  
**Young Ki Lee**, Gyunggi-do (KR); **Tae Hyun Kim**,  
Gyunggi-do (KR); **Si Joong Yang**, Gyunggi-do (KR); **Jong Man Kim**,  
Gyunggi-do (KR); **Kyu Kwan Oh**, Gyunggi-do (KR); **Young Ho Sohn**,  
Gyunggi-do (KR)
- (73) Assignee: **Samsung Electro-Mechanics Co., Ltd.**,  
Suwon, Gyeonggi-Do (KR)

D364,384	S	*	11/1995	Shimizu et al.	.....	D13/182
D364,385	S	*	11/1995	Shimizu et al.	.....	D13/182
6,078,501	A	*	6/2000	Catrambone et al.	.....	361/704
D441,726	S	*	5/2001	Sofue et al.	.....	D13/182
D448,739	S	*	10/2001	Iwasaki et al.	.....	D13/182
D476,959	S	*	7/2003	Yamada et al.	.....	D13/182
7,425,757	B2	*	9/2008	Takubo	.....	257/678
D587,662	S	*	3/2009	Soutome et al.	.....	D13/182
D589,012	S	*	3/2009	Soyano et al.	.....	D13/182
D606,951	S	*	12/2009	Soyano et al.	.....	D13/182
D648,290	S	*	11/2011	Mori	.....	D13/182
D653,633	S	*	2/2012	Soyano	.....	D13/182
D653,634	S	*	2/2012	Soyano	.....	D13/182
D674,760	S	*	1/2013	Mochizuki et al.	.....	D13/182
D686,174	S	*	7/2013	Soyano	.....	D13/182
2001/0038143	A1	*	11/2001	Sonobe et al.	.....	257/690
2010/0149774	A1	*	6/2010	Matsumoto et al.	.....	361/783
2011/0044012	A1	*	2/2011	Matsumoto	.....	361/728

(\*\*) Term: **14 Years**

\* cited by examiner

(21) Appl. No.: **29/450,498**

*Primary Examiner* — Elizabeth J Oswecki

(22) Filed: **Mar. 18, 2013**

(74) *Attorney, Agent, or Firm* — McDermott Will & Emery LLC

(30) **Foreign Application Priority Data**

Dec. 6, 2012 (KR) ..... 30-2012-0058592

(51) **LOC (10) CL.** ..... **13-03**

(52) **U.S. CL.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/110, 182; 361/713, 714, 715, 728,  
361/736, 752, 774, 775, 783, 784, 785,  
361/813; 257/668, 678, 684, 690  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,408,128 A \* 4/1995 Furnival ..... 257/690  
D364,383 S 11/1995 Yamada et al.

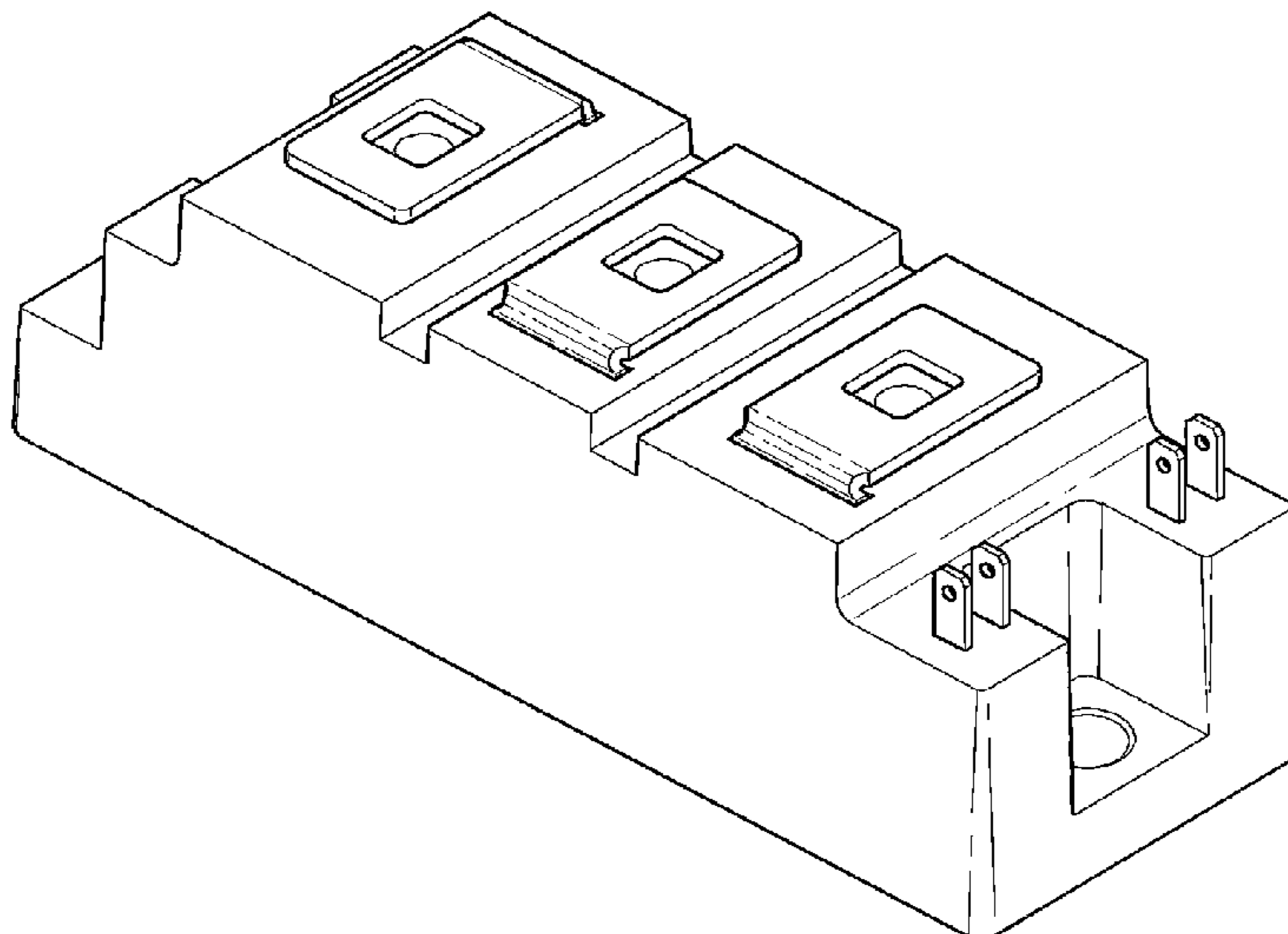
(57) **CLAIM**

The ornamental design for a power semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a power semiconductor module showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a left-side view thereof;  
FIG. 5 is a right-side view thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.

**1 Claim, 4 Drawing Sheets**



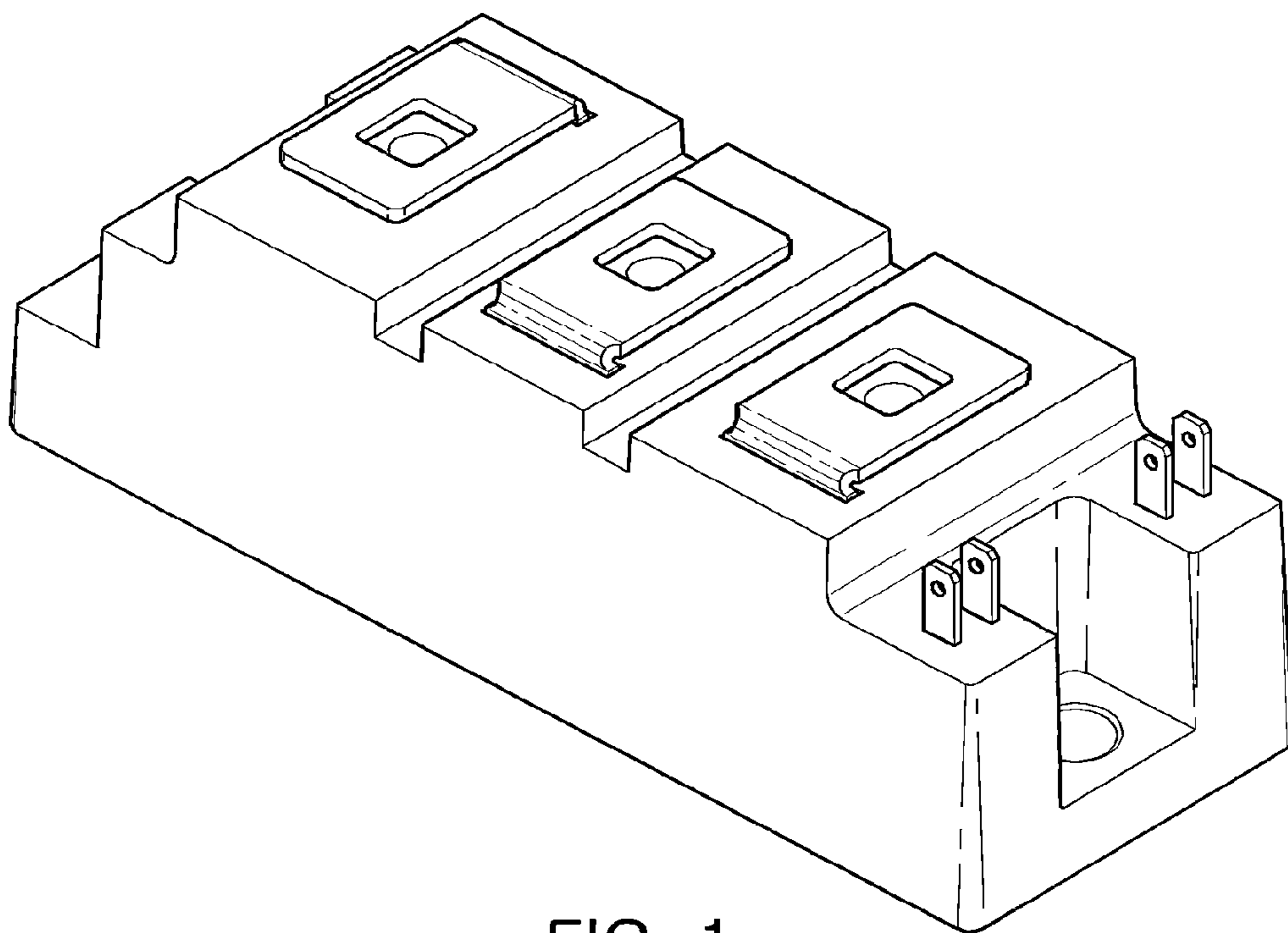


FIG. 1

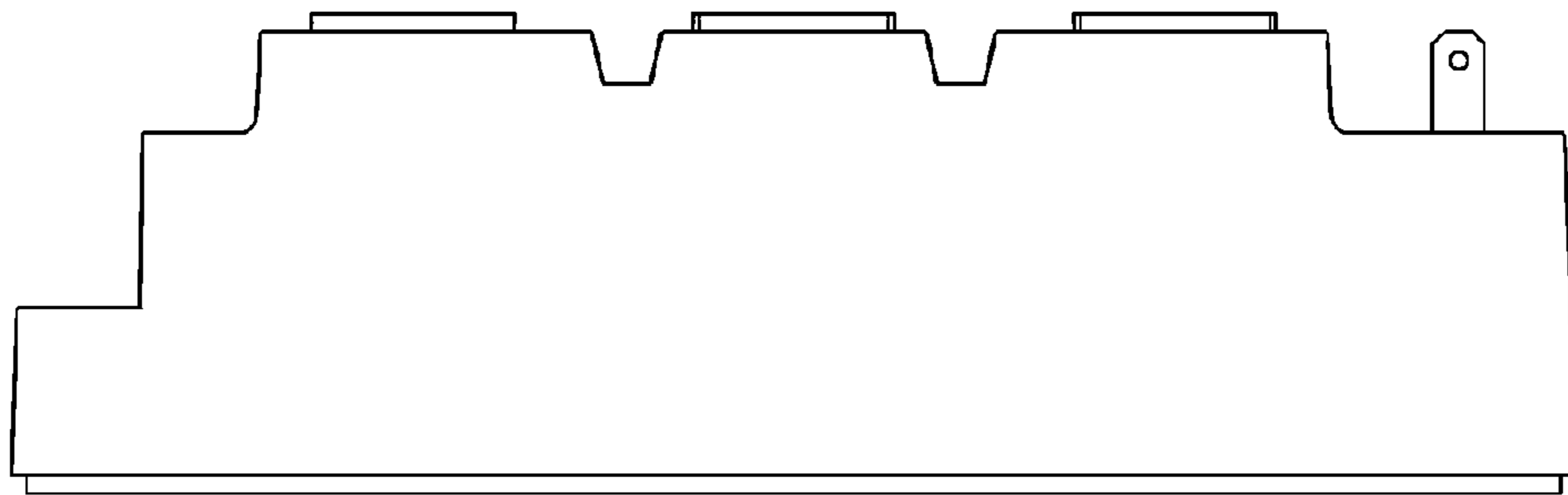


FIG. 2

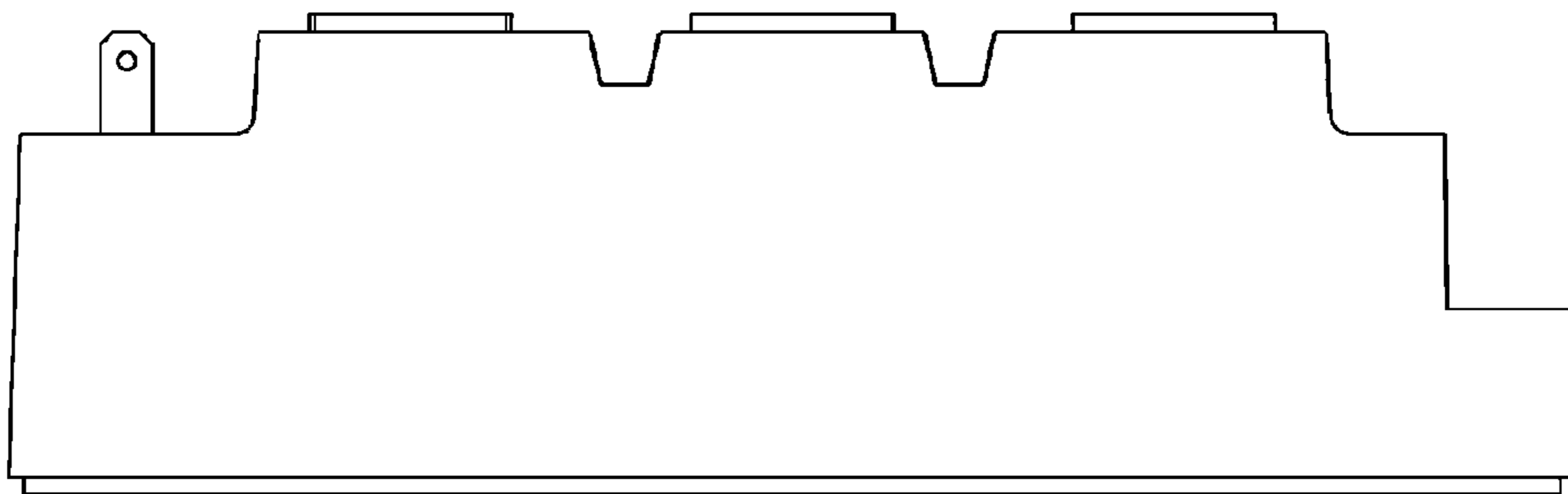


FIG. 3

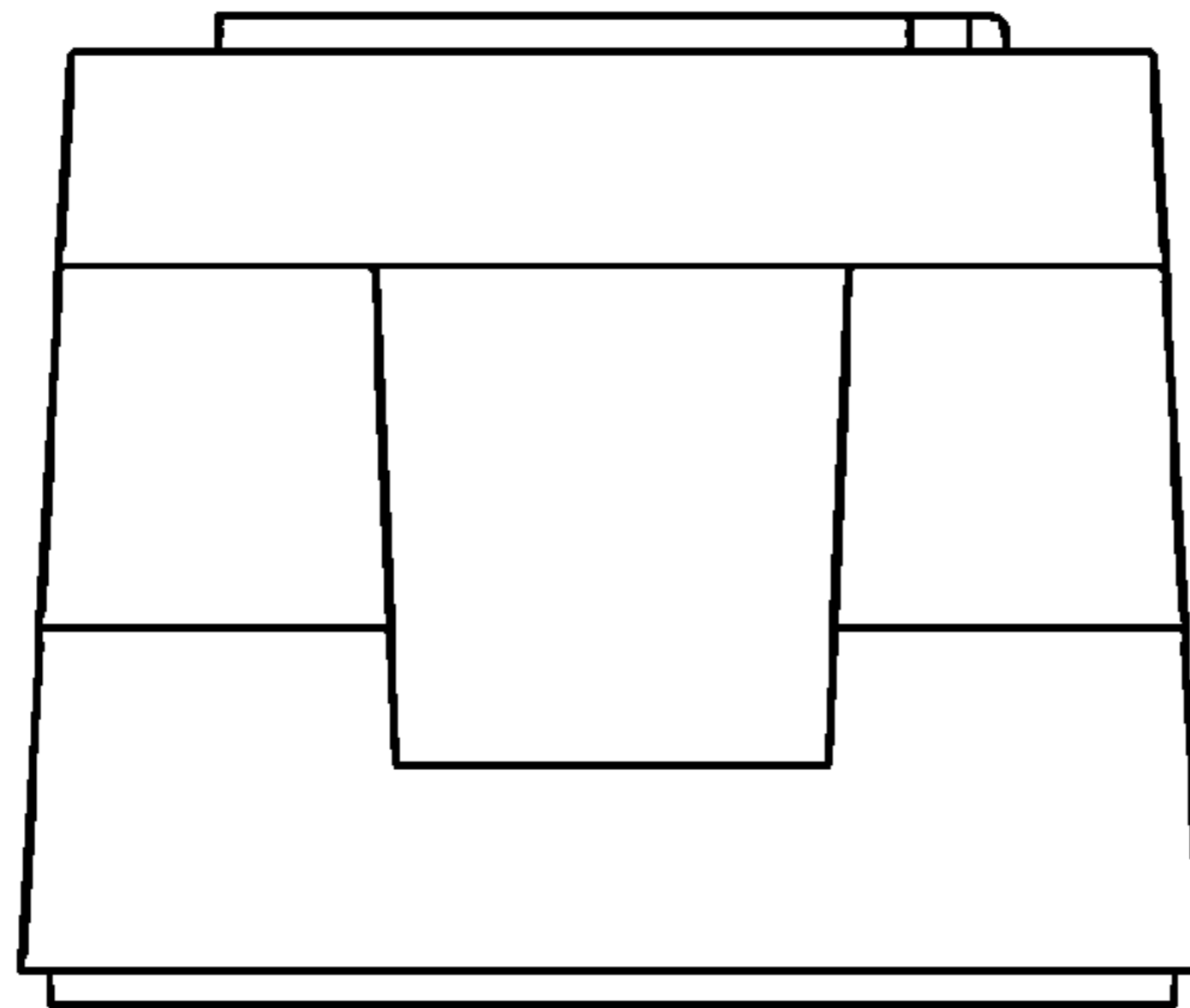


FIG. 4

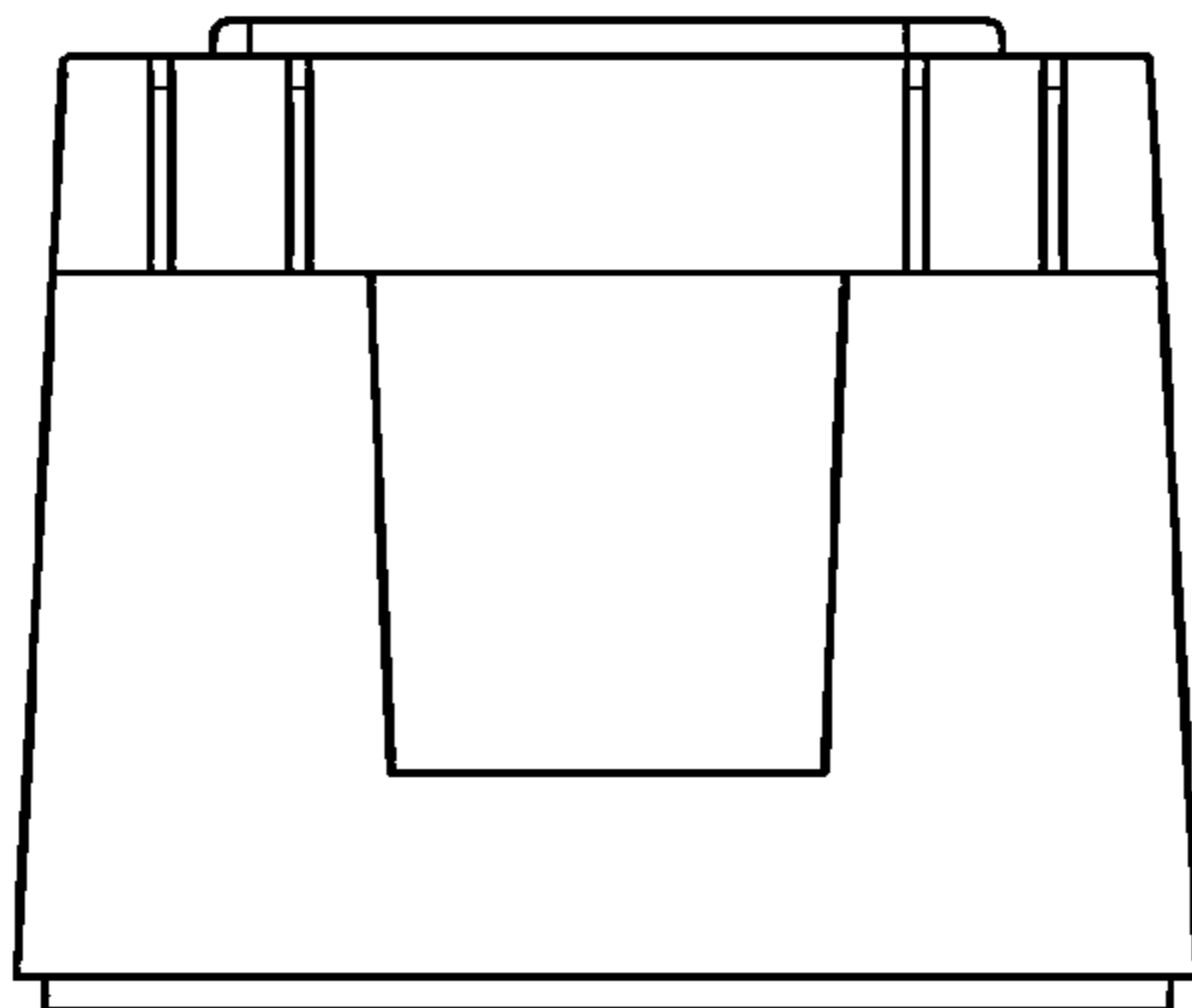


FIG. 5

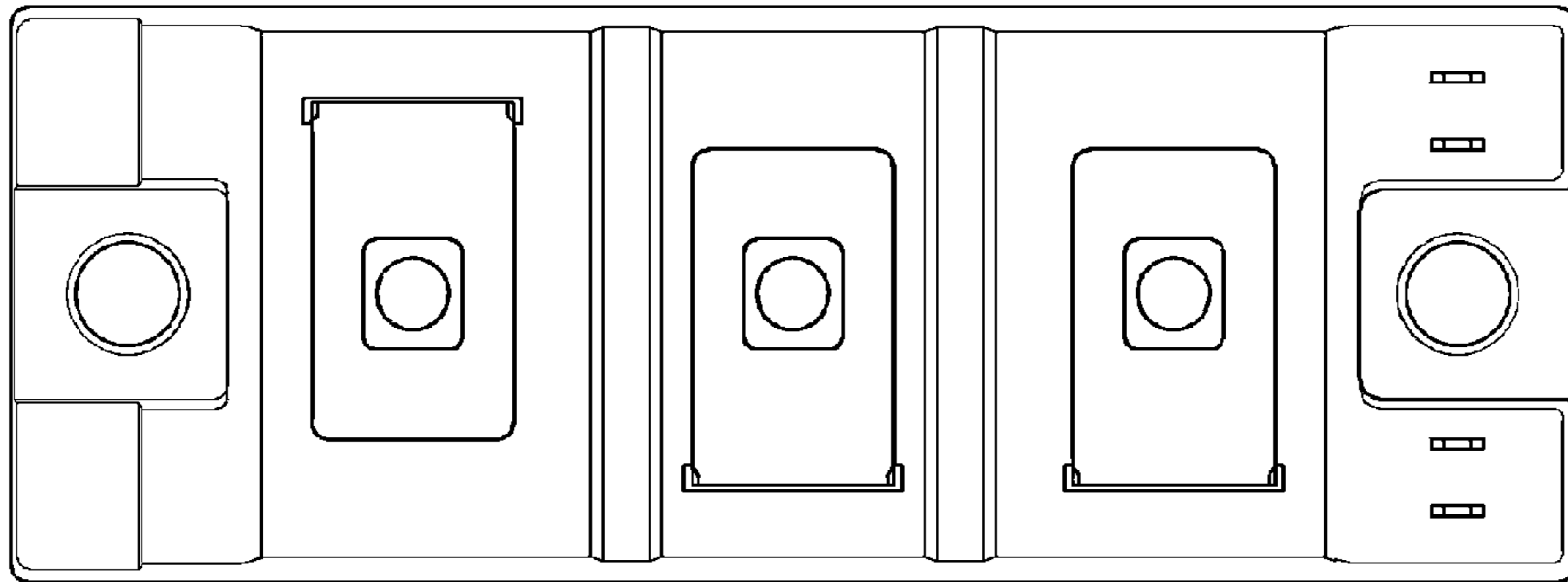


FIG. 6

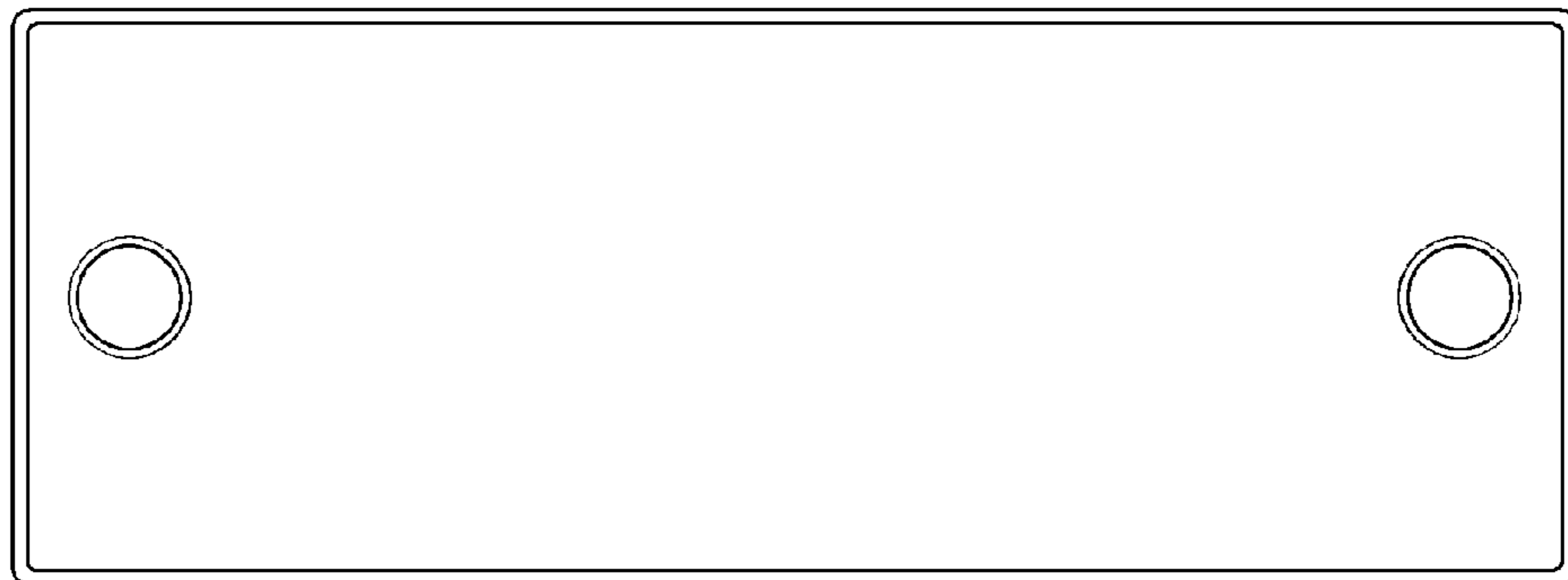


FIG. 7

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : D703,625 S  
APPLICATION NO. : 29/450498  
DATED : April 29, 2014  
INVENTOR(S) : Jae Hyun Lim et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, item (72) Inventors should read: Jae Hyun LIM, Gyunggi-do (KR); Young Ki Lee, Gyunggi-do (KR); Tae Hyun Kim, Gyunggi-do (KR); Si Joong Yang, Gyunggi-do (KR); Jong Man Kim, Gyunggi-do (KR); Kyu ~~Kwan~~ Hwan Oh, Gyunggi-do (KR); Young Ho Sohn, Gyunggi-do (KR).

Signed and Sealed this  
Second Day of September, 2014



Michelle K. Lee  
*Deputy Director of the United States Patent and Trademark Office*